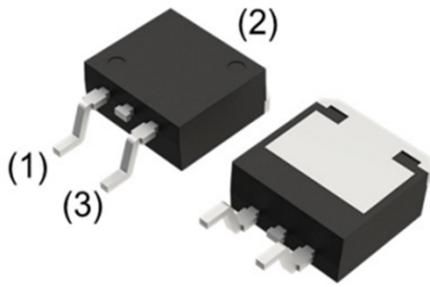


# TO-263 (D2PAK)

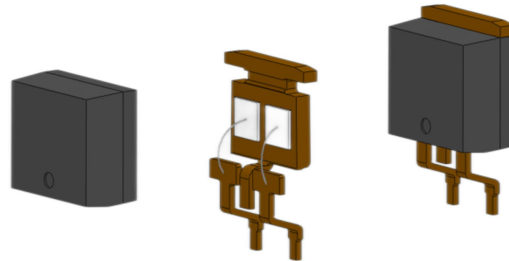
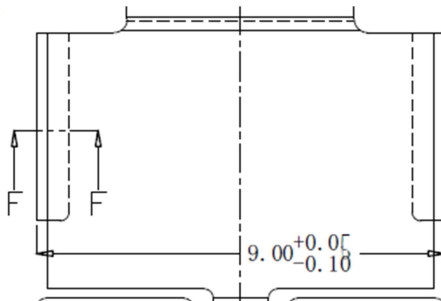


TO-263 (D2PAK)

## 1: Certification

- System:
  - IATF 16949
  - ISO9001
  - ISO14001
  - ISO45001
- ROHS/REACH/ELV:
  - Lead frame、Wire, Molding compound、Post plating.
- UL 94: V-0
- MSL : level 1
- Whisker Test: JESD 201 class 1A
- AEC-Q101 (Rev E): Qualified Available
- Solder bath temperature : 275°C maximum, 10 s

## 2: Internal Structure Diagram



## Meet Die Size

Die Pad(mm)	Die size(mm)	
X=8.50, Y=5.65	Double die (Max)	Single die(Max)
	X=3.50, Y=5.30	X=7.50, Y=5.30

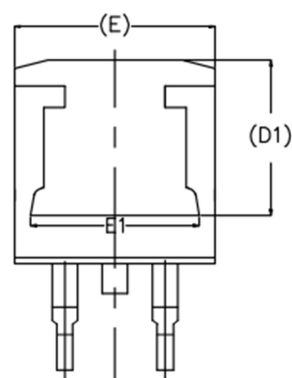
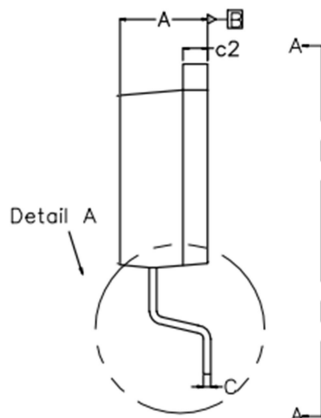
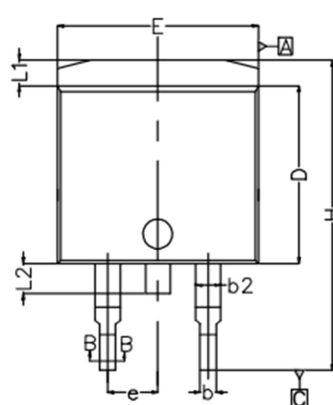
## 3: Reliability Experiment

	Test	Test Condition
1	Temperature Cycle (TMCL)	500 cycles at -55°C to 150°C
2	Unbiased Highly Accelerated Stress Test (UHST)	96 hours at Ta = 130°C, RH = 85% ;P=2.27atm.
3	High Temperature, Humidity & Reverse Bias (THBS)	1000 hours at Tj = 85°C, RH = 85%, Reverse Bias = 80% rated voltage
4	Thermal Fatigue (TFAT)	10000 cycles, Tj = 25°C to 125°C, DTj ≥ 80°C, Id=depends on device & Ton = Toff ~2.5 to 3.5 mins.
5	Static High Temperature Life (SHTL)	1000 hours – Tj = max operating temp, Reverse Bias = 80% / 100% rated voltage.(according to customer request).
6	High Temperature Storage (HTSL)	1000 hours at Ta = 150°C or Ta=175°C

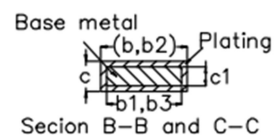
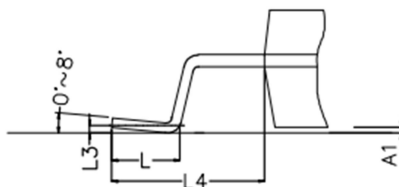
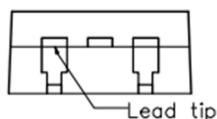
# TO-263 (D2PAK)

## 4: Package Outline Dimensions in millimeters

### 4.1 POD



Section A-A



SYMBOL	MILLIMETERS			NOTES		SYMBOL	MILLIMETERS			NOTES
	Normal	MIN.	MAX.				Normal	MIN.	MAX.	
A	4.55	4.35	4.75			D1	7.75	7.50	8.0	
A1	0.12	0	0.25			E	10.18	10.0	10.4	
b	0.85	0.69	<b>0.94</b>			E1	8.57	8.25	8.80	
b1	0.83	0.69	0.88			e	2.54	2.54BSC		
b2	1.33	1.20	1.45			H	15.20	15.00	15.60	
b3	1.33	1.20	1.45			L	2.64	2.50	2.79	
c	0.50	0.38	<b>0.53</b>			L1	1.35	1.0	1.65	
c1	0.48	0.38	0.56			L2	1.51	1.27	1.78	
c2	1.27	1.14	1.40			L3	0.25	0.25BSC		
D	8.75	<b>8.51</b>	9.02			L4	5.03	4.78	5.28	